

Specification for TFT

AFL16080A0-0.96INTM-ANO





Α	Orient Display
FL	TFT Type
16080	Resolution 160 x 80
A0	Serial A0
0.96	0.96", Module Dimension 30.0 x 24.0 x 5.0 mm
1	IPS Display
N	Top: -20~+70°C; Tstr: -30~+80°C
Т	Transmissive
М	Normal Brightness, 300cd/m2
/	Controller <u>ST7735S</u>
ANO	SPI Interface + compatible Arduino













DOCUMENT REVISION HISTORY:

DATE	PAGE	DESCRIPTION
2020.10.3	-	First release

Tel: (425)698-1938 Fax: (425)698-1852

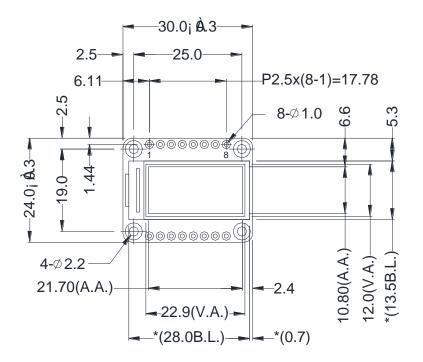
Contents

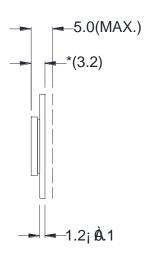
- 1. General Specification
- 2. Mechanical Drawing
- 3. Block Diagram
- 4. Interface Pin Function
- 5. Absolute Maximum Ratings
- 6. Electrical Characteristics
- 7. Optical Characteristics
- 8. Timing Characteristics
- 9. Standard Specification for Reliability
- 10. General Precautions
- 11. Specification of Quality Assurance
- 12. Packing Method

1. General Specification

Item	Dimension	Unit
Module dimension	30.0 x 24.0 x 5.0(MAX)	mm
View area	22.9 x 12.0	mm
Active area	21.70 x 10.80	mm
Dot pitch	0.1356 x 0.135	mm
Number of Dots	160 x 80(RGB)	dots
LCD TYPE	TFT, Transmissive	
Top Polarizer Type	Glare	
View direction	All View	
Drive IC	ST7735S	
Interface Type	SPI 4-wires	
Backlight Type	1 White LED	
Touch Panel	Not Available	

2. Mechanical Drawing

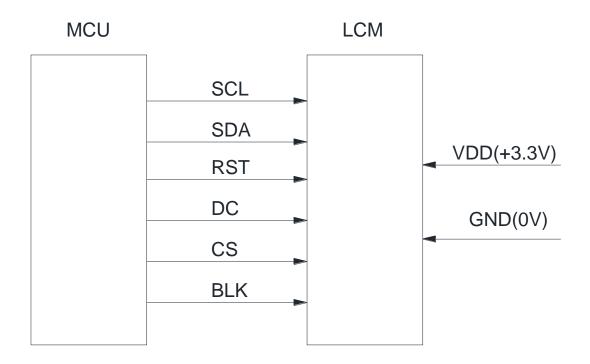




*ST7735S or equivalent

*()dimension for reference only

3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Level	Description
1	GND	0V	Ground
2	V_{DD}	3.3V	Supply Voltage for logic
3	SCL	H/L	Serial Clock
4	SDA	H/L	Serial Data
5	RST	H/L	Reset, signal is active low
6	DC	H/L	H:Display data or Parameter, L:Command Data
7	CS	H/L	Chip Select, signal is active low
8	BLK	H/L	Backlight control, H:turn on ,L: turn off

5.Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit
Supply Voltage	VDD	-0.3	4.6	V
Input Voltage(logic input)	V _{In}	-0.3	VDD+0.3	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Tstr	-30	80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any time. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

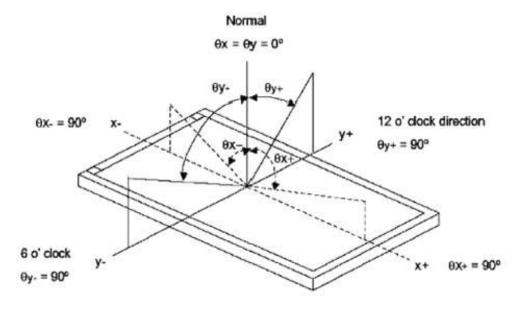
6. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage	$V_{ m DD}$	_	2.7	3.3	3.6	V
Input Voltage for Logic	V_{io}	-	0	-	3.6	V
Input High Volt.	V_{IH}	_	$0.7~V_{DD}$	_	V_{DD}	V
Input Low Volt.	V_{IL}	_	V_{SS}	_	$0.3 \text{ V}_{\text{DD}}$	V

7. Optical Characteristics

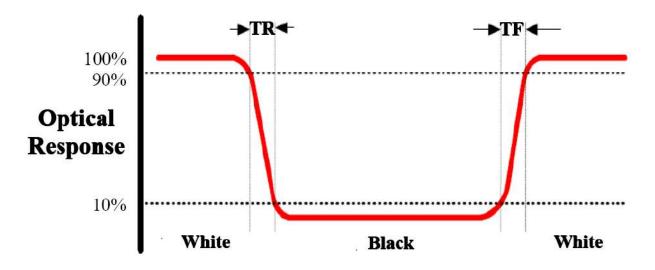
Item		Symbol	Condition	Min	Тур	Max	Unit
Luminance	Luminance		_	300	_	_	Cd/m ²
Contrast Ratio		CR	θ=0°	_	500:1	_	_
Response Time		T on	25℃		30		me
Response Time		T off	250		30	-	ms
		W _X		0.255	-	0.330	
	White	W_{Y}		0.255	-	0.330	
	Red	R _X					
Color Filter		R _Y					
Chromacicity		G _X					
		G _Y					
		B _X					
	Blue	B _Y					
	11	Θ _x -			80		
Viewing angle	Hor.	Θ _{x+}	00 40		80		
	.,	О у+	CR>10		80		
	Ver.	Θ _y .			80		
Uniformity		Un	_	80	-		%

Note1:Definition of Viewing Angle θx and θy :



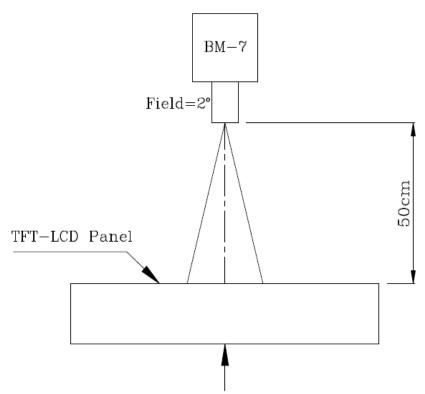
Note 2: Definition of contrast ratio CR:

Note 3: Definition of Response Time(Tr,Tf):



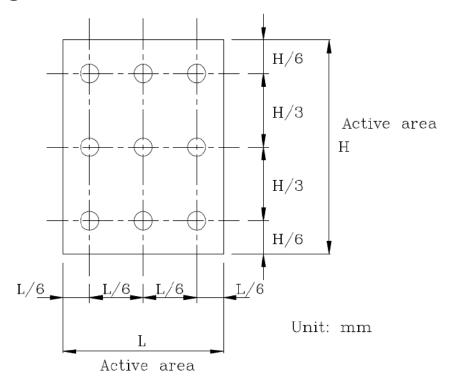
Note 4: Definition of Luminance:

1 The Brightness Test Equipment Setup Field=2°(As measuring "black" image, field=2°is the best testing condition)

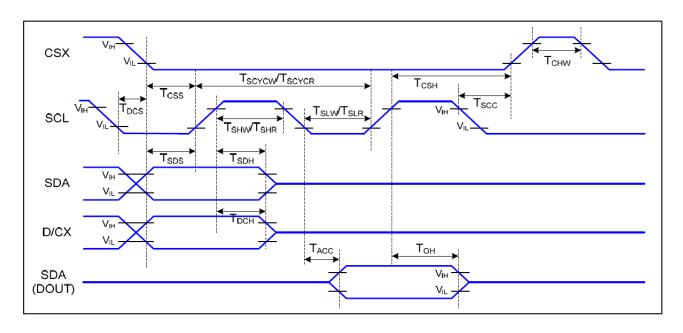


The center of the screen

2 The Brightness Test Point Setup



8. Timing Characteristics



Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	TCSS	Chip Select Setup Time (Write)	45		ns	
	TCSH	Chip Select Hold Time (Write)	45		ns	
CSX	TCSS	Chip Select Setup Time (Read)	60		ns	
	TSCC	Chip Select Hold Time (Read)	65		ns	
	TCHW	Chip Select "H" Pulse Width	40		ns	
	TSCYCW	Serial Clock Cycle (Write)	66		ns	-Write Command &
	TSHW	SCL "H" Pulse Width (Write)	15		ns	Data Ram
SCL	TSLW	SCL "L" Pulse Width (Write)	15		ns	Data Kalii
SCL	TSCYCR	Serial Clock Cycle (Read)	150		ns	-Read Command &
	TSHR	SCL "H" Pulse Width (Read)	60		ns	-Read Command & Data Ram
	TSLR	SCL "L" Pulse Width (Read)	60		ns	Data Raili
D/CX	TDCS	D/CX Setup Time	10		ns	
DICX	TDCH	D/CX Hold Time	10		ns	
SDA	TSDS	Data Setup Time	10		ns	
	TSDH	Data Hold Time	10		ns	For Maximum CL=30pF
(DIN) (DOUT)	TACC	Access Time	10	50	ns	For Minimum CL=8pF
(5001)	ТОН	Output Disable Time	15	50	ns	

9. Standard Specification for Reliability

9.1Standard Specification for Reliability of LCD Module

No	Test Item	Condition	Remarks
1	High Temperature	$Ts = +70^{\circ}C$, 96 hours	IEC60068-21:2007
	Operation		GB2423.2-2008
2	Low Temperature	$Ts = -20^{\circ}C$, 96 hours	IEC60068-2-1:2007
	Operation		GB/2423.1-2008
3	High Temperature	$Ta = +80^{\circ}C$, 96 hours	IEC60068-21:2007
	Storage		GB/2423.2-2008
4	Low Temperature	$Ta = -30^{\circ}C$, 96 hours	IEC60068-21:2007
	Storage		GB/2423.1-2008
5	Storage at High	$Ta = +60^{\circ}C$, 90% RH max,48 hours	IEC60068-2-78 :2001
	Temperature and		GB/T2423.3—2006
	Humidity		
6	Thermal	-20°C 30 min~+70°C 30 min,	Start with cold
	Shock	Change time:5min, 10 Cycle	temperature,
	(nonoperation)		End with high
			temperature,
			IEC60068-214:1984,
			GB/2423.22-2002
7	ESD	C=150pF,R=330 Ω ,5point/panel	IEC61000-42:2001
		Air: \pm 8Kv,5times;	GB/T17626.2-2006
		Contact: ±4Kv,5times	
		(Environment:15°C~35°C,	
		30%~60%.86Kpa~106Kpa)	
8	Vibration Test	Frequency range:10~55Hz	IEC60068-2-6:1982
		Stroke:1.5mm	GB/T2423.101995
		Sweep:10Hz~55Hz~10Hz	
		2 hours for each direction of X.Y.Z	
		(6 hours for total)	
9	Mechanical	Half Sine Wave60G	IEC60068-2-27:1987
	Shock (Non	6ms, $\pm X, \pm Y, \pm Z$	GB/T2423.5—1995
	Op)	3times for each direction	
10	Package Drop	Height:80cm,	IEC60068-2-32:1990
	Test	1corner,3 edges,6 surfaces	GB/T2423.8—1995

Note1: Ts is the temperature of panel's surface.

Note2: Ta is the ambient temperature of sample.

9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
1	Current	Refer To	The current consumption should conform to the
	Consumption	Specification	product specification.
2	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
3	Appearance	Visual inspection	Defect free.

9.3MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage
	conditions room temperature (25 \pm 5 °C), normal humidity (50 \pm 10%
	RH), and
	in area not exposed to direct sun light.

10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by ODNA.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

Electrical-Optical Characteristics: According to the individual specification to test the product.

Appearance Characteristics: According to the individual specification to test the product.

Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

Test method: According to MIL-STD105E.General Inspection Level II take a

single Time.

The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 1.5 Total defects: AQL = 1.5

10.3 Non-conforming Analysis & Deal with Manners

10.3.1 Non-conforming Analysis

Purchaser should provide the data detail of non-conforming sample and the non-conforming.

After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.

If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

If any product defect be found during assembling, supplier must change the good for every defect after confirmation.

Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

10.4 Agreement items

Both parties should negotiate together when the following problems happen.

There is any problem of standard of quality assurance, and both sides should agree that it must be modified.

There is any argument item which does not record in the standard of quality assurance.

Any other special problem.

10.5 Standard of The Product Appearance Test

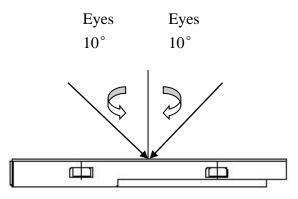
10.5.1Manner of appearance test

The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at 30 ± 5 cm.

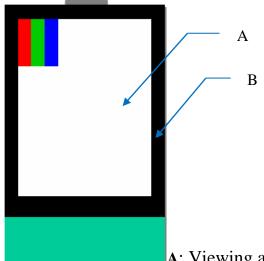
When test the model of transmissive product must add the reflective plate.

The test direction is based on around 10° of vertical line.

Temperature: 25±5°C Humidity: 60±10%RH



Definition of area:



A: Viewing area B: Outside viewing area

10.5.2 Basic principle

When the standard cannot be described, AQL will be applied.

The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.

New item must be added on time when it is necessary.

10.6 Inspection Specification

NO.	Item	Criterion					AQL
1	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect.1.2 Missing character, dot or icon.1.3 Display malfunction.					0.65
		1.4 No function or no displ	av.				
		1.5 Current consumption ex	-	luct spec	ificati	ons.	
		1.6 LCD viewing angle def	-	1			
		1.7 Mixed product types.					
		1.8 Flicker					
2	Black or	2.1 White and black or cold	or spots on	display	≤ 0.2	25mm, no	1.5
	White	more than					
	spots	Five spots.					
	or Bright	2.2 Densely spaced: No mo	re than thre	ee spots v	<i>w</i> ıthın	3mm.	
	spots or Color spots						
	on LCD						
	(Display						
	only)						
3	LCD and	3.1 Round type: As following drawing					1.5
	Touch	$\Phi = (X+Y)/2$					
	Panel black		Size(mm			eptable Q'ty	
	spots,	$\mathbf{x}_{i}\mathbf{x}_{i+1}$	Φ ≦ 0.10)	Acc	ept no dense	
	white	→ + +	0.10< Ф	≤0.20	2		
	spots, contaminati	lacksquare	0.20< Ф	≤ 0.25	2		
	on (non -	Ť	0.25< Ф	≤ 0.30	1		
	display)		0.30< Ф		0		
		* Densely spaced: No more	than two s	pots witl	nin 3n	nm.	
		3.2 Line type: (As followin	g drawing)				1.5
			Length(Width(mm)	Acceptable	
			mm)		′	Q'ty	
				W≦0.0)2	Accept no	
		∠ <u></u> w				dense	
		~ ^ <u>*</u> ~	L≦3.0	0.02 < W	<i>I</i> ≦	2	
		→ _L		0.05			
			L≦2.5	0.03 <w< td=""><td><i>J</i>≦</td><td>2</td><td></td></w<>	<i>J</i> ≦	2	
				0.08			
		0.08 <w rejection<="" td=""></w>					
		* D 1 N	41 4 1		: 2		
		* Densely spaced: No more	tnan two l	ines with	ın 3n	ım.	

If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction Follow NO.3 -2 Line Type Symbols: x: Chip length y: Chip with k: Seal width t: Glass thich L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surfate.	idth z: Chip thickness ckness a: LCD side leng		1.5
Follow NO.3 -2 Line Type Symbols: x: Chip length y: Chip with k: Seal width t: Glass thick L: Electrode pad length 6.1 General glass chip:	$0.30 < \Phi \le 0.50$ $0.50 < \Phi \le 1.00$ $1.00 < \Phi$ Total Q' ty be. idth z: Chip thickness ckness a: LCD side length	dense	1.5
Follow NO.3 -2 Line Type Symbols: x: Chip length y: Chip with k: Seal width t: Glass thich L: Electrode pad length 6.1 General glass chip:	$0.50 < \Phi \le 1.00$ $1.00 < \Phi$ $Total Q' ty$ Total Chip thickness ckness a: LCD side length	0 0 0 0	1.5
Symbols: x: Chip length y: Chip with k: Seal width t: Glass think L: Electrode pad length 6.1 General glass chip:	1.00< Φ Total Q' ty be. idth z: Chip thickness ckness a: LCD side length	0 0	1.5
Symbols: x: Chip length y: Chip with k: Seal width t: Glass think L: Electrode pad length 6.1 General glass chip:	Total Q' ty oe. idth z: Chip thickness ckness a: LCD side leng	gth	1.5
Symbols: x: Chip length y: Chip with k: Seal width t: Glass think L: Electrode pad length 6.1 General glass chip:	idth z: Chip thickness ckness a: LCD side leng	gth	1.5
Symbols: x: Chip length y: Chip with k: Seal width t: Glass think L: Electrode pad length 6.1 General glass chip:	idth z: Chip thickness ckness a: LCD side leng		1.5
x: Chip length y: Chip wik: Seal width t: Glass thic L: Electrode pad length 6.1 General glass chip:	ckness a: LCD side leng		1.5
$Z \le 1/2t$ $1/2t < z \le 2t$ ① Unit: mm ② If there are 2 or more 6.1.2 Corner crack: $Z \le 1/2t$ $Z \le 1/2t$	Not over viewing area Not exceed 1/3k chips, x is the total lengery: Chip width Not over viewing area	$x \le 2MM$ $x \le 2MM$ gth of each chip x: Chip length $x \le 2MM$	
	$Z \le 1/2t$ 1/2t< $z \le 2t$ ∴ Unit: mm ∴ If there are 2 or more 6.1.2 Corner crack: $Z \le 1/2t$ $Z \le 1/2t$ ∴ Unit: mm ∴ Unit: mm	$Z \le 1/2t$ Not over viewing area $1/2t < z \le 2t$ Not exceed $1/3k$ \odot Unit: mm \odot If there are 2 or more chips, x is the total len 6.1.2 Corner crack:	$Z \le 1/2t $

NO.	Item	Criterion			AQL
7	Glass	Symbols:			1.5
	crack	x: Chip length y: Chip width z: Chip thickness			
	k: Seal width t: Glass thickness a: LCD side length				
		L: Electrode pad length			
		7.2 Protrusion over terminal:			
		7.2.1 Chip on electrode pad:			
			Z		
		y: Chip width	x: Chip length	z: Chip thickness	
		$y \le 0.5$ mm	$x \le 2MM$	0< z ≦ t	
		7.2.2	1		
		Non-conductive portio	n:		
		y X	1 z y	↑ Z	
		y: Chip width	x: Chip length	z: Chip thickness	
		y≦L	$x \le 2MM$	$0 < z \le t$	
		• If there chipped are	ea touches the ITO term	inal, over 2/3 of the ITO	
			spected according to ele		
		• If the product will	be heat sealed by the cu	stomer, the alignment	
		mark must mot be dam		_	
		7.2.3 Substrate protube	erance and internal crack	k	
		, X	y: width x:	length	
			y ≤ 1/3L X	≦2MM	
		y			

NO.	Item	Criterion	AQL	
8	Cracked glass	No crack is allowed.		
9	Backlight elements			
10	Bezel	No scratches with W>0.1 and Length>2.5mm.	1.5	
11	PCB、 COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination.	1.5	
		11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram.	1.5 1.5	
		11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places.	1.5	
		11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts.	0.65	
		11.6 The jumper on the PCB should conform to the product characteristic chart.	0.65	
12	FPC	FPC damage per IPC guidelines.(IPC-A-610) Nicks or damage along the edges of the flexible printed cir-cuitry and cutouts, providing the penetration does not exceed 50% of the distance from the edge to the nearest conductor to 2.5mm[0.1in], Whichever is less.	1.5	
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.	1.5	
		13.2 No short circuits in components on PCB or FPC. 13.3 Soldering per IPC guidelines.(IPC-A-610)	1.5 0.65	

NO.	Item	Criterion			AQL	
14	Touch	Symbols:			1.5	
	Panel	x: Chip length y: Chip width z: Chip thickness				
	Chipped	k: Seal width t: Touch Panel Total thickness a: LCD side length				
	glass	L: Electrode pad length				
			14.1 General glass chip:			
		14.1.1 Chip on panel su	rface and crack betwee	n panels:		
		X y k X X X X X X X X X X X X X X X X X				
		z: Chip thickness	y: Chip width	x: Chip length		
		Z≦t	$\leq 1/2$ k and not over	$x \le 2MM$		
			viewing area			
		⊙ Unit: mm				
		① If there are 2 or mo	re chips, x is the total le	ngth of each chip		
		14.1.2 Corner crack:	r r r	8r		
		X Z Z Y				
		z: Chip thickness	y: Chip width	x: Chip length		
		Z≦t	$\leq 1/2$ k and not over	$x \le 2MM$		
			viewing area			
		⊙ Unit: mm				
		⊙ If there are 2 or more chips, x is the total length of each chip				

NO.	Item	tem Criterion		
NO. 15	Touch Panel(Fish eye, dent and bubble on film)	CriterionSIZE(mm)Acceptable Q' ty $\Phi \le 0.2$ Accept no dense $0.2 < D \le 0.4$ 5 $0.4 < D \le 0.5$ 0		1.5
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch pand line distortion ($\leq 2.5\%$), it is accept		1.5
17	Touch Panel Linearity	Less than 1.5% is acceptable.		1.5
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g		1.5
19	General appearance	19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet.		0.65 0.65 0.65 0.65

11. Handling Precaution

11.1 Handling of LCM

Avoid external shock.

Don't apply excessive force on the surface.

Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid is attaching to your hand, skin, cloth, etc., wash it thoroughly and immediately.

Don't operate it above the absolute maximum rating.

Don't disassemble the LCM.

The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

The modules should be kept in antistatic bags or other containers resistant to static for storage.

The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

Store it in an ambient temperature of $25\pm10^{\circ}$ C, and in a relative

humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.

Store it in a clean environment, free from dust, active gas, and solvent.

Store it in anti-static electricity container.

Store it without any physical load.

11.3 Soldering

Use only soldering irons with proper grounding and no leakage.

Iron: no higher than 280±10°C and less than 3 sec during hand soldering.

Rewiring: no more than 2 times.

12.PackingMethod

TBD